

MEC1-130-02-L-D-EM2

MEC1-120-02-L-D-RA1-SL

MEC1-120-02-F-D-EM2

(1.00 mm) .0394"

MEC1-RA, MEC1-EM SERIES

RIGHT-ANGLE/EDGE MOUNT SOCKETS

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MEC1-RA

Insulator Material:

Black LCP

Contact Material:

Phosphor Bronze

Plating:

Au or Sn over 50 μ " (1.27 μ m) Ni

Current Rating:

1.6 A per pin (2 adjacent pins powered)

Operating Temp Range:

-55 °C to +125 °C

Insertion Depth:

(5.84 mm) .230" to (8.13 mm) .320"

RoHS Compliant:

Yes

PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (05-40)

(0.15 mm) .006" max (50-70)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



FILE NO. E111594

MEC1 - 1 POSITIONS PER ROW - CARD SLOT - PLATING OPTION - D - RA1 - NP - SL

Mates with:

(1.60 mm)

.062" card

05, 08, 20, 30,
40, 50, 60, 70

-02

= (1.60 mm)

.062" thick card

-F

= Gold flash on contact,

Matte Tin on tail

-L

= 10 μ "(0.25 μ m) Gold on contact,

Matte Tin on tail

POSITIONS PER ROW	POLARIZED POSITIONS
05	3, 4
08	5, 6
20	15, 16
30	21, 22
40	31, 32
50	41, 42
60	31, 32, 63 & 64
70	53, 54, 115 & 116

-NP

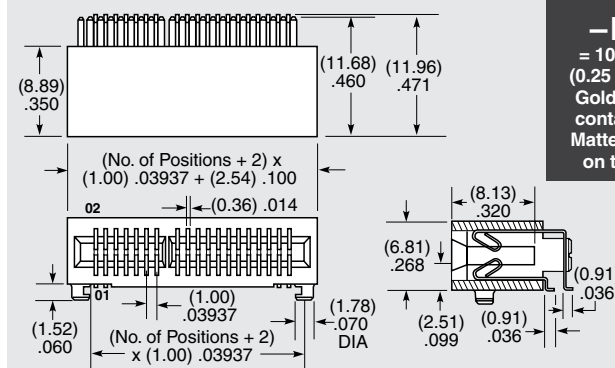
= No Polarization (8 positions only)

Leave Blank for polarization

ALSO AVAILABLE
(MOQ Required)

- Elevated body height
 - Other platings
- Contact Samtec.

Note: While optimized for 50 Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75 Ω applications. Contact Samtec for further information.



Note: Some sizes, styles and options are non-standard, non-returnable.

APPLICATION

Samtec recommends that pads on the mating board be Gold plated.

HIGH-SPEED CHANNEL PERFORMANCE

MEC1-RA

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

15
Gbps

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MEC1-EM

Insulator Material:

Black LCP

Contact Material:

Phosphor Bronze

Plating:

Au or Sn over 50 μ " (1.27 μ m) Ni

Current Rating:

1.8 A per pin (2 adjacent pins powered)

Operating Temp Range:

-55 °C to +125 °C

Insertion Depth:

(5.84 mm) .230" to (8.13 mm) .320"

RoHS Compliant:

Yes

Lead-Free Solderable:

Yes

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



FILE NO. E111594

MEC1 - 1 POSITIONS PER ROW - 02 - PLATING OPTION - D - EM2 - NP

Mates with:

(1.60 mm)

.062" card

05, 08, 20, 30,
40, 50, 60, 70

-F

= Gold flash on contact, Matte Tin on tail

-L

= 10 μ " (0.25 μ m) Gold on contact, Matte Tin on tail

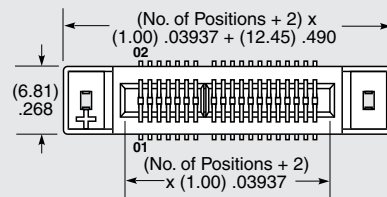
-NP

= No Polarization (8 positions only)

Leave Blank for polarization

ALSO AVAILABLE
(MOQ Required)

- Edge mount leads for (0.80 mm) .031" thick board
 - Other platings
- Contact Samtec.



Note: Some sizes, styles and options are non-standard, non-returnable.

Note: While optimized for 50 Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75 Ω applications. Contact Samtec for further information.

POSITIONS PER ROW	POLARIZED POSITIONS
05	3, 4
08	5, 6
20	15, 16
30	21, 22
40	31, 32
50	41, 42
60	31, 32, 63 & 64
70	53, 54, 115 & 116